

MOSFET – N-Channel, POWERTRENC[®], SyncFET[™]

30 V, 14.8 A, 6.0 mΩ

FDMC7672S

General Description

This FDMC7672S is produced using onsemi's advanced POWERTRENC process that has been especially tailored to minimize the on-state resistance. This device is well suited for Power Management and load switching applications common in Notebook Computers and Portable Battery packs.

Features

- Max $R_{DS(on)}$ = 6.0 mΩ at $V_{GS} = 10\text{ V}$, $I_D = 14.8\text{ A}$
- Max $R_{DS(on)}$ = 7.1 mΩ at $V_{GS} = 4.5\text{ V}$, $I_D = 12.4\text{ A}$
- High Performance Technology for Extremely Low $R_{DS(on)}$
- Pb-Free, Halide Free and RoHS Compliant

Applications

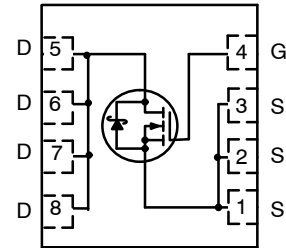
- DC-DC Buck Converters
- Notebook Battery Power Management
- Load Switch in Notebook

MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

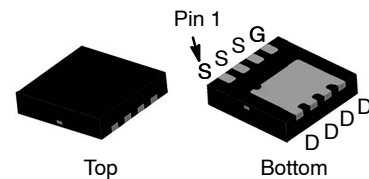
Symbol	Parameter	Value	Unit
V_{DS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	± 20	V
I_D	Drain Current: Continuous, $T_C = 25^\circ\text{C}$ Continuous, $T_A = 25^\circ\text{C}$ (Note 1a) Pulsed	18 14.8 45	A
E_{AS}	Single Pulse Avalanche Energy (Note 3)	60	mJ
P_D	Power Dissipation: $T_C = 25^\circ\text{C}$ $T_A = 25^\circ\text{C}$ (Note 1a)	36 2.3	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

V_{DS}	$R_{DS(on)}$ MAX	I_D MAX
30 V	6.0 mΩ @ 10 V	14.8 A
	7.1 mΩ @ 4.5 V	

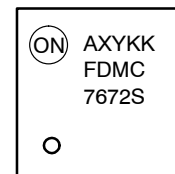


N-CHANNEL MOSFET



**WDFN8 3.3 × 3.3, 0.65P
CASE 511DQ
(Option A)**

MARKING DIAGRAM



A = Assembly Location
XY = 2-Digit Date Code
KK = 2-Digit Lot Run Traceability Code
FDMC7672S = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping [†]
FDMC7672S	WDFN8 (Pb-Free, Halide Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

FDMC7672S

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	3.5	$^{\circ}\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	53	

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 1\text{ mA}, V_{GS} = 0\text{ V}$	30	–	–	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 10\text{ mA}$, referenced to 25°C	–	12	–	$\text{mV}/^{\circ}\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}$	–	–	1	mA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$	–	–	100	nA

ON CHARACTERISTICS (Note 2)

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 1\text{ mA}$	1.2	1.6	3.0	V
$\Delta V_{GS(th)} / \Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 10\text{ mA}$, referenced to 25°C	–	–6	–	$\text{mV}/^{\circ}\text{C}$
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}, I_D = 14.8\text{ A}$	–	5.0	6.0	$\text{m}\Omega$
		$V_{GS} = 4.5\text{ V}, I_D = 12.4\text{ A}$	–	6.1	7.1	
		$V_{GS} = 10\text{ V}, I_D = 14.8\text{ A}, T_J = 125^{\circ}\text{C}$	–	5.9	9.0	
g_{FS}	Forward Transconductance	$V_{DS} = 5\text{ V}, I_D = 14.8\text{ A}$	–	78	–	S

DYNAMIC CHARACTERISTICS

C_{iss}	Input Capacitance	$V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	–	1895	2520	pF
C_{oss}	Output Capacitance		–	770	1025	pF
C_{rss}	Reverse Transfer Capacitance		–	85	130	pF
R_g	Gate Resistance	$f = 1\text{ MHz}$	–	1.2	3.2	Ω

SWITCHING CHARACTERISTICS

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 15\text{ V}, I_D = 14.8\text{ A}, V_{GS} = 10\text{ V}, R_{GEN} = 6\text{ }\Omega$	–	11	21	ns
t_r	Rise Time		–	4	10	ns
$t_{d(off)}$	Turn-Off Delay Time		–	26	42	ns
t_f	Fall Time		–	3	10	ns
Q_g	Total Gate Charge	$V_{GS} = 0\text{ V to }10\text{ V}, V_{DD} = 15\text{ V}, I_D = 14.8\text{ A}$	–	30	42	nC
		$V_{GS} = 0\text{ V to }4.5\text{ V}, V_{DD} = 15\text{ V}, I_D = 14.8\text{ A}$	–	14	20	nC
Q_{gs}	Gate to Source Gate Charge	$V_{DD} = 15\text{ V}, I_D = 14.8\text{ A}$	–	5.3	–	nC
Q_{gd}	Gate to Drain "Miller" Charge	$V_{DD} = 15\text{ V}, I_D = 14.8\text{ A}$	–	4.0	–	nC

FDMC7672S

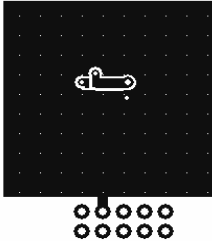
ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS						
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 14.8\text{ A}$ (Note 2)	–	0.8	1.3	V
		$V_{GS} = 0\text{ V}, I_S = 1.9\text{ A}$ (Note 2)	–	0.5	1.2	
t_{rr}	Reverse Recovery Time	$I_F = 14.8\text{ A}, di/dt = 300\text{ A}/\mu\text{s}$	–	29	45	ns
Q_{rr}	Reverse Recovery Charge		–	28	44	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NOTES:

- $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 53°C/W when mounted on a 1 in² pad of 2 oz copper.



b) 125°C/W when mounted on a minimum pad of 2 oz copper.

- Pulse Test: Pulse Width < 300 μs , Duty cycle < 2.0%.
- E_{AS} of 60 mJ is based on starting $T_J = 25^\circ\text{C}$, $L = 1\text{ mH}$, $I_{AS} = 11\text{ A}$, $V_{DD} = 27\text{ V}$, $V_{GS} = 10\text{ V}$. 100% test at $L = 3\text{ mH}$, $I_{AS} = 4.8\text{ A}$.

TYPICAL CHARACTERISTICS

($T_J = 25^\circ\text{C}$ unless otherwise noted)

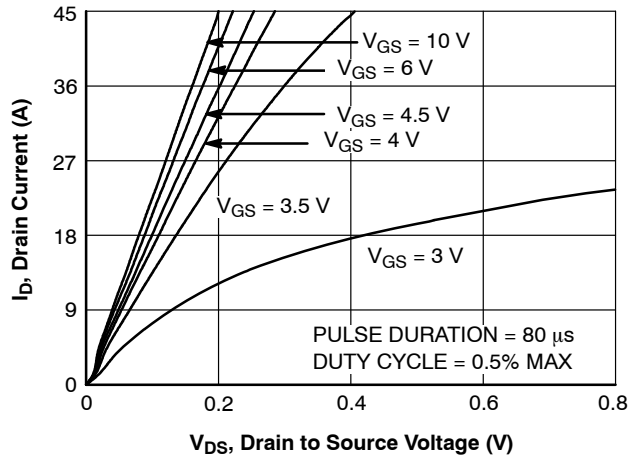


Figure 1. On-Region Characteristics

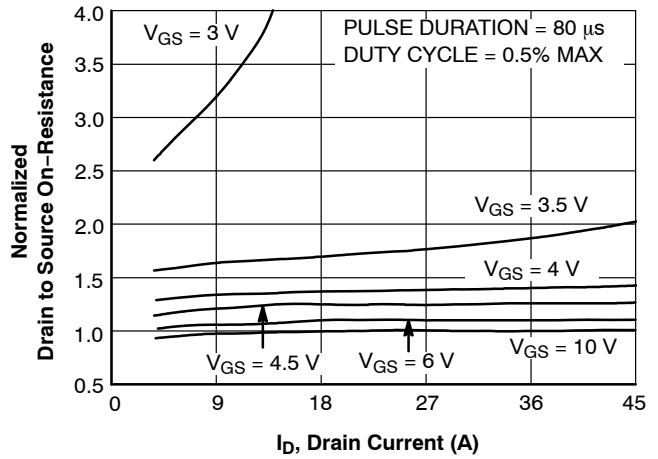


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

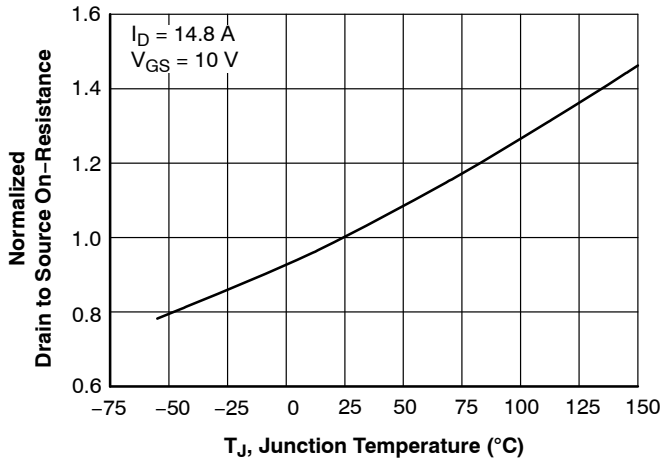


Figure 3. Normalized On-Resistance vs. Junction Temperature

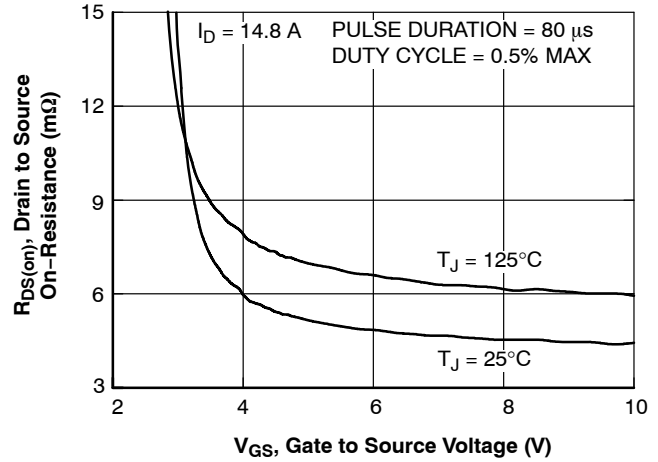


Figure 4. On-Resistance vs. Gate to Source Voltage

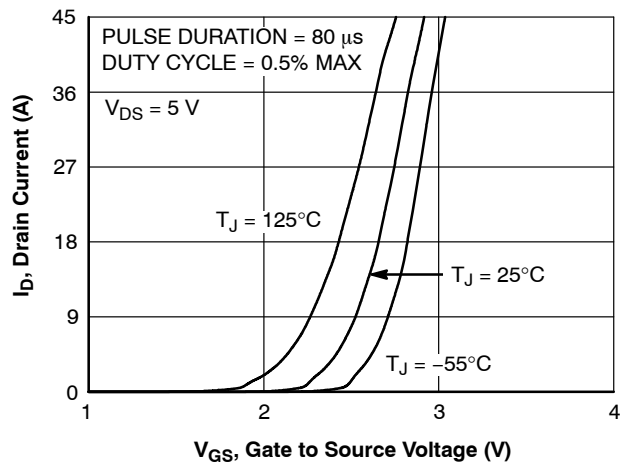


Figure 5. Transfer Characteristics

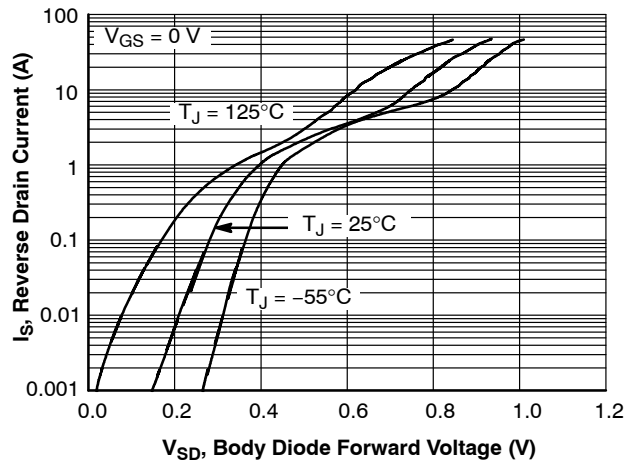


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

TYPICAL CHARACTERISTICS (continued)

($T_J = 25^\circ\text{C}$ unless otherwise noted)

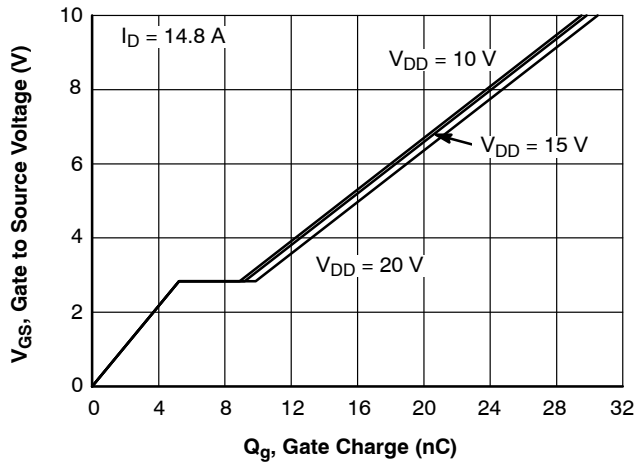


Figure 7. Gate Charge Characteristics

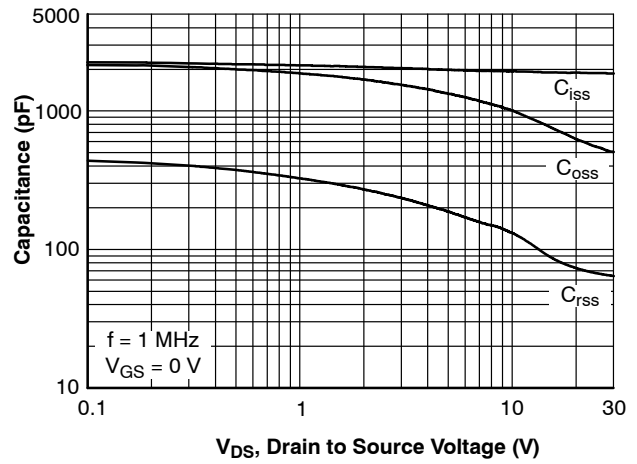


Figure 8. Capacitance vs. Drain to Source Voltage

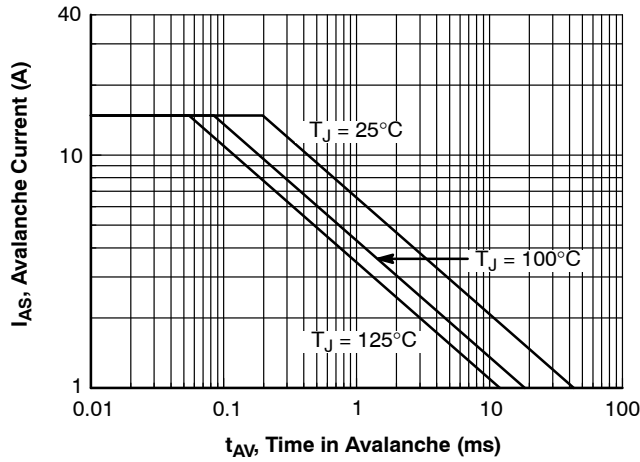


Figure 9. Unclamped Inductive Switching Capability

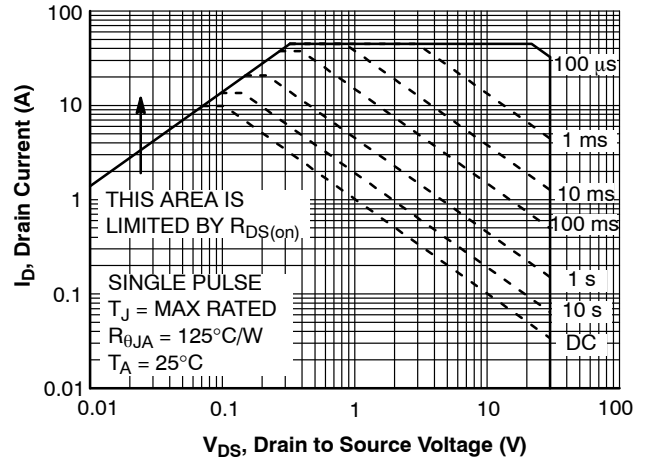


Figure 10. Forward Bias Safe Operating Area

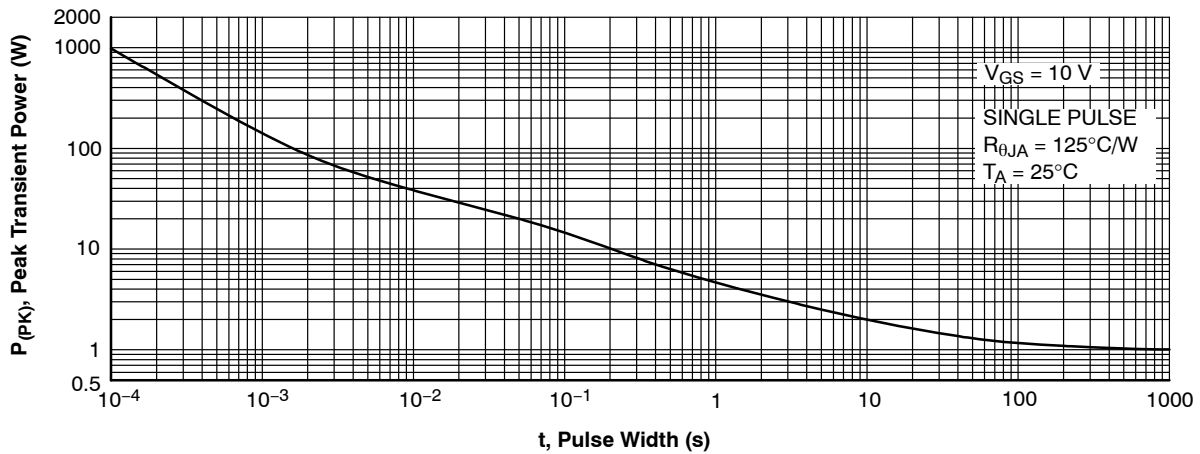
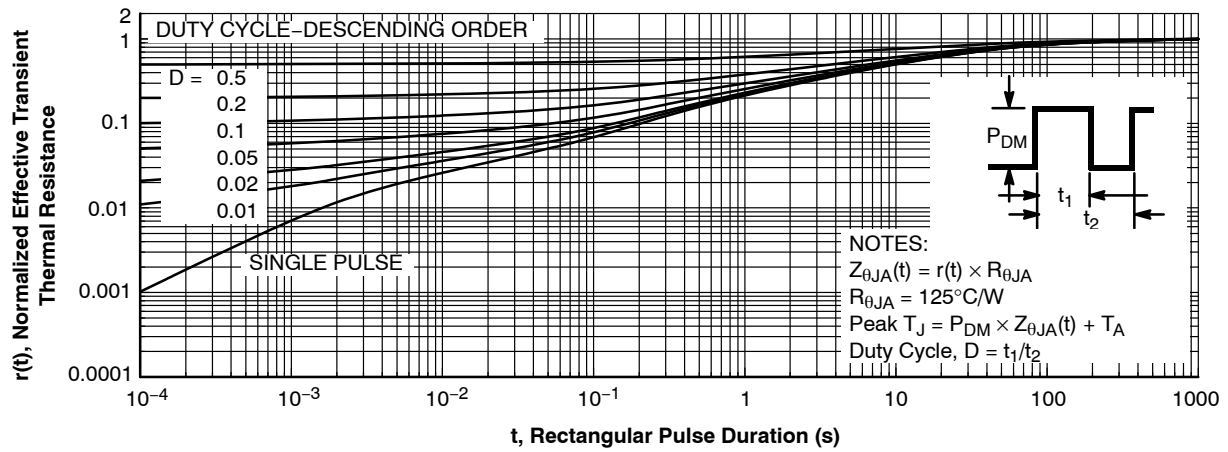


Figure 11. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS (continued)

($T_J = 25^\circ\text{C}$ unless otherwise noted)



TYPICAL CHARACTERISTICS (continued)

SyncFET Schottky Body Diode Characteristics

onsemi's SyncFET process embeds a Schottky diode in parallel with POWERTRENCH MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 13 shows the reverse recovery characteristic of the FDMC7672S.

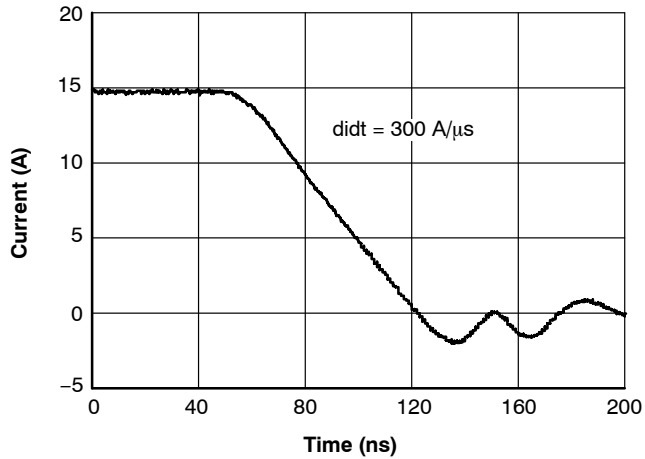


Figure 13. SyncFET Body Diode Reverse Recovery Characteristics

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

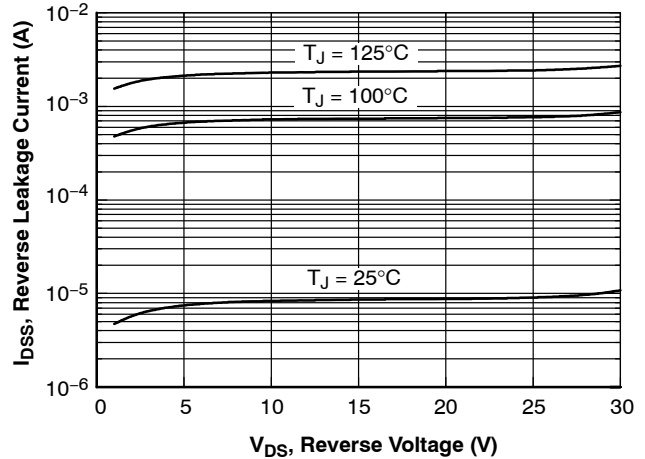


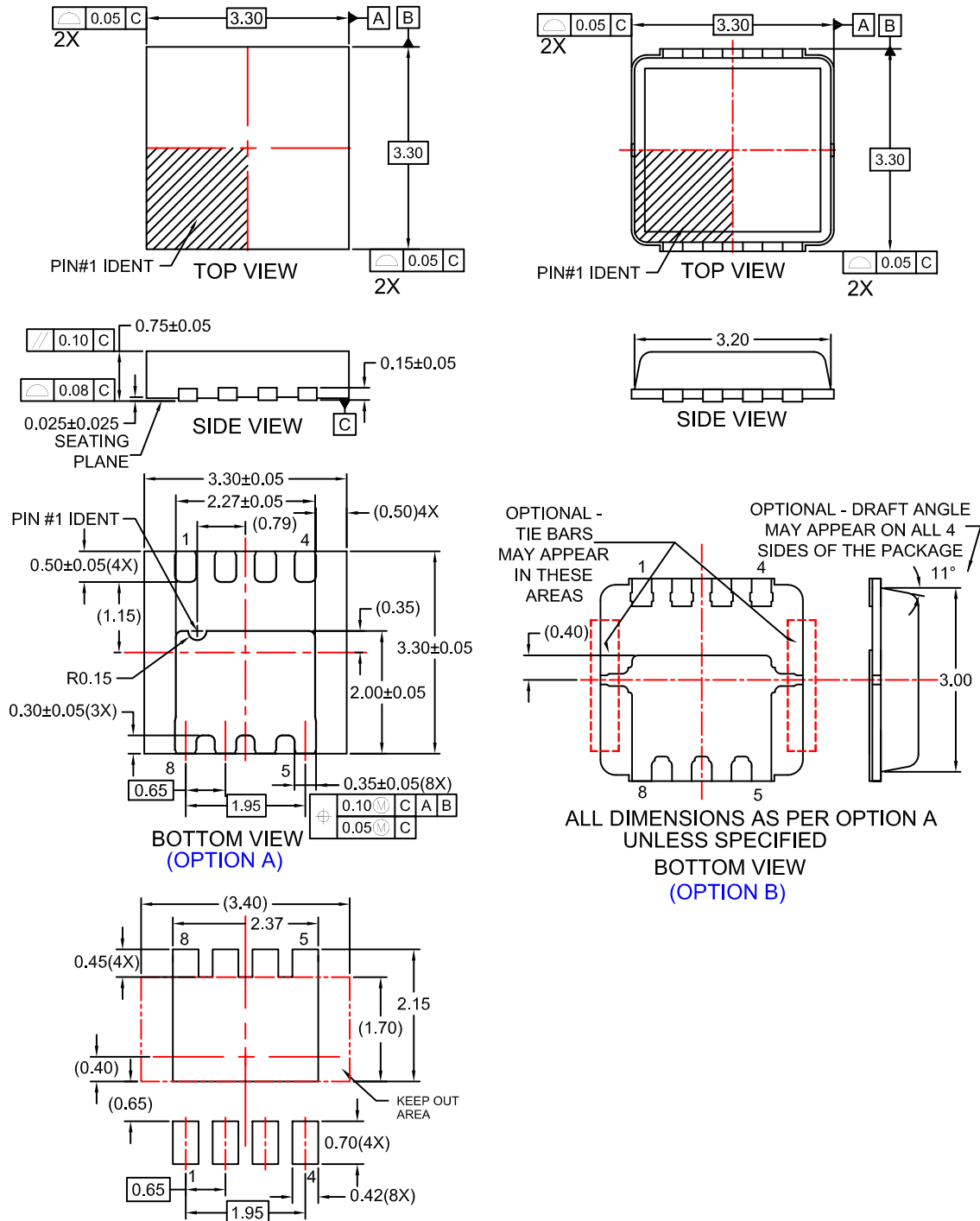
Figure 14. SyncFET Body Diode Reverse Leakage vs. Drain-Source Voltage

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WDFN8 3.3x3.3, 0.65P
CASE 511DQ
ISSUE O

DATE 31 OCT 2016



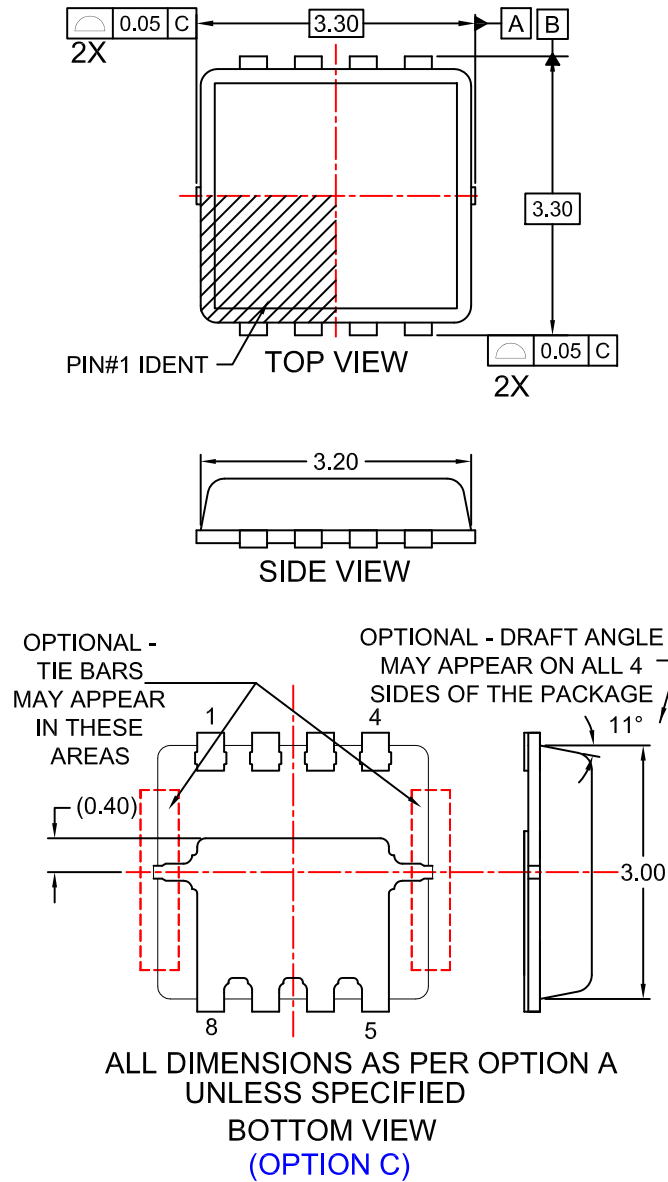
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CASE 511DQ
ISSUE O

DATE 31 OCT 2016



NOTES:

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